



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 6849**
Takeshi HASHIMOTO et al. : Docket No. 2001_1790
Serial No. 10/029,991 : Group Art Unit 1712
Filed December 31, 2001 : Examiner M. Zimmer

THERMOSETTING LOW-DIELECTRIC
RESIN COMPOSITION AND USE THEREOF

COPY

REQUEST FOR ACKNOWLEDGMENT OF CLAIM FOR PRIORITY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the Notice of Allowability, it was stated that none of the copies of the certified priority documents have been received. However, in the summary of the Official Action dated April 10, 2003 it was acknowledged that all certified copies of the priority documents were received in Serial No. 09/433,281 i.e. the parent of this application.


Under these circumstances, Applicants are entitled to the benefit of these priority applications. Also see M.P.E.P. §201.14(b) in the paragraph bridging pages 200-90 and 200-91.

A copy of the Claim for Priority in this application with stamped postcard receipt as proof of filing is enclosed.

Accordingly, prompt acknowledgment of this Claim for Priority and acknowledgment of receipt of priority documents referred to therein is respectfully requested.

Respectfully submitted,

Takeshi HASHIMOTO et al.

By: 
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October 14, 2003



UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Takeshi HASHIMOTO et al.

Serial No. [NEW]

Filed December 31, 2001

THERMOSETTING LOW-DIELECTRIC
RESIN COMPOSITION AND USE
THEREOF

(Rule 1.53(b) Divisional of Serial No.
09/433,281, Filed November 3, 1999)

Attn: Application Branch

Attorney Docket No. 2001-1790

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

CLAIM OF PRIORITY UNDER 35 USC 119

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Applicants in the above-entitled application hereby claim the date of priority under the International Convention of Japanese Patent Application No. 331977/98, filed November 6, 1998, Japanese Patent Application No. 331978/98, filed November 6, 1998, Japanese Patent Application No. 331979/98, filed November 6, 1998, and Japanese Patent Application No. 331980/98, filed November 6, 1998, as acknowledged in the Declaration of this application.

Certified copies of said Japanese Patent Applications are of record in parent application Serial No. 09/433,281, filed November 3, 1999.

Respectfully submitted,

Takeshi HASHIMOTO et al.

By Matthew Jacob
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Parent Due Date: January 5, 2002

OUR REF: 2001-1790/MJ/00755

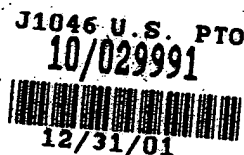
Applicant: Takeshi HASHIMOTO et al.

Serial No.: [NEW] Filing Date: December 31, 2001

Title: THERMOSETTING LOW-DIELECTRIC RESIN COMPOSITION AND USE THEREOF

Receipt of the following papers is acknowledged:

1. Utility Patent Application Transmittal (Rule 53(b) divisional of USSN 09/433,281, filed November 3, 1999)
2. Patent Office Fee Transmittal Form [in duplicate]
3. Specification comprising pages (including claims 1-11 and abstract)
4. Copy of executed Declaration and Power of Attorney from parent application
5. Information Disclosure Statement and Form PTO 1449
6. Claim of Priority Under 35 USC 119
7. Check in the amount of \$740.00.



Date: December 31, 2001

Attorney: MJ/pjm

[Check No. 98189]